

[HOLE DRILLING METHOD AND APPARATUS]

Abstract

A method and apparatus for drilling a hole through a printed circuit board is described using a laser beam such that the diameter of the top portion and the bottom portion of the hole are substantially equal. The laser beam is irradiated perpendicularly to a printed circuit board to drill a tapered hole having a top portion and a bottom portion wherein the diameter of the bottom portion is smaller than that of the top portion. Further, the laser beam 10 is irradiated to the tapered hole obliquely relative to the board 12 to equalize the diameters of the top and bottom portions to each other. By irradiating the laser beam 10 obliquely, a straight hole 14 can be formed.